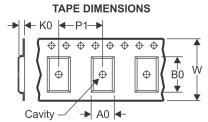
To request a full data sheet, please send an email to: <a href="mailto:display-contact@list.ti.com">display contact@list.ti.com</a>.

PACKAGE MATERIALS INFORMATION

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# TAPE AND REEL INFORMATION





Α0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

## QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

All differsions are norminal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS65198RUYR	WQFN	RUY	28	3000	330.0	12.4	4.25	4.25	1.15	8.0	12.0	Q2
TPS65198RUYR	WQFN	RUY	28	3000	330.0	12.4	4.25	4.25	1.15	8.0	12.0	Q2
TPS65198RUYT	WQFN	RUY	28	250	180.0	12.4	4.25	4.25	1.15	8.0	12.0	Q2
TPS65198RUYT	WQFN	RUY	28	250	180.0	12.4	4.25	4.25	1.15	8.0	12.0	Q2

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\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS65198RUYR	WQFN	RUY	28	3000	367.0	367.0	35.0
TPS65198RUYR	WQFN	RUY	28	3000	367.0	367.0	35.0
TPS65198RUYT	WQFN	RUY	28	250	210.0	185.0	35.0
TPS65198RUYT	WQFN	RUY	28	250	210.0	185.0	35.0

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